CONTENT

ADSP MEMORY MAP

ADSP MEMORY MAP - SHORT FORM

TIMING ADSP 2100 - SYSTEM 4 BOARD

PARTS LIST SPECIFICATION:

ASSY, SUB, DRIVER ADSP - D.SIMU. - REV/B
SCHEMATIC DRIVER ADSP - REV/B

PARTS LIST SPECIFICATION:

ASSY, SUB, ADSP II PCB - H.D. - REV/C

ASSY, ADSP II PCB - H.D. COMP. - REV/B

ASSY, ADSP II PCB - H.D. RACE - REV/C

ASSY, ADSP II PCB - R. D. PANO. - REV/A

FABRICATION ADSP II - REV/A

ASSEMBLY ADSP II - REV/C

SCHEMATIC ADSP II PCB - REV/C

Driver ADSP Board, Rev 1 Uses ADSP-2100 Rev 3 68010 Stuff:

jram Memory:

To Access Program Memory Set Flag ADSPBR Low. Program Memory is accessed as 8K Longwords with the low 24 bits used. Set Flag ADSPBR High.

The ADSP Program Memory is accessible immediately after setting ADSPBR Low.

Data Memory:

===

To Access Data Memory Set Flag ADSPBR Low. Data Memory is accessed as 8K Words. Set Flag ADSPBR High.

The ADSP Data Memory is accessible immediately after setting ADSPBR Low.

Sequential Output Memory:

Set /BCON Low - The 68010 sees Sequential Output Memory #1.
The ADSP-2100 sees Sequential Output Memory #2.

Set /BCON high - The 68010 sees Sequential Output Memory #2.

The ADSP-2100 sees Sequential Output Memory #1.

Program Memory 0000 - 1FFF (8K x 24)

a Memory 0000 - 1FFF (8K x 16)

2000 SIMBUF Read the Sequential Input Memory; Increment the Address.

It is necessary to follow a SIMBUF read with two NOPs (or other instructions) before doing another SIMBUF read.

2001 SIMLD Write Data to Sequential Input

Memory Address Counter

Write Data to Sequential Output

It is necessary to follow a SIMLD write with two NOPs (or other instructions) before doing a SIMBUF read.

2002 SOMD Write Data to Sequential Output Memory; Increment Address

It is necessary to follow a SOMD write with one NOP (or other instruction) before doing another SOMD write.

SOMLD

		Memory Address Counter
2005	XOUT	Write D0 to Latch which can be read by 68010
2006	GINT	Generate 68010 Interrupt 2
2007	MPAG E	Write DMD0 to Memory Page Select (For Sequential Input Memory)

Notes: 1. 2000 and 2004 must be READ only.

2003

2. 2001, 2002, 2003, 2005, 2006, and 2007 should be WRITTEN to only.

3. The Sequential Input Memory consists of two 64K Word Pages, Selected by MPAGE. Sequential access will not cross the page.

4. The Sequential Output Memory is actually two independent memories. The 68010 selects which one is used by whom.

ADSP Memory Map - Short Form

Program Memory 0000 - 1FFF (8K x 24)

Data Memory 0000 - 1FFF (8K x 16)

2000

2002

2003

Memory; Increment the Address.

It is necessary to follow a SIMBUF read with two NOPs (or other instructions) before doing another SIMBUF read.

2001 SIMLD Write Da

SIMBUF

SOMD

SOMLD

Write Data to Sequential Input Memory Address Counter

Write Data to Sequential Output

Write Data to Sequential Output

Memory; Increment Address

Read the Sequential Input

It is necessary to follow a SIMLD write with two NOPs (or other

instructions) before doing a SIMBUF read.

It is necessary to follow a SOMD write with one NOP (or other

instruction) before doing another SOMD write.

		Memory Address Counter
2005	XOUT	Write D0 to Latch which can be read by 68010
2006	GINT	Generate 68010 Interrupt 2
2007	MPAGE	Write DMD0 to Memory Page Select (For Sequential Input Memory)

Notes: 1. 2000 and 2004 must be READ only.

2. 2001, 2002, 2003, 2005, 2006, and 2007 should be WRITTEN to only.

3. The Sequential Input Memory consists of two 64K Word Pages, Selected by MPAGE. Sequential access will not cross the page.

4. The Sequential Output Memory is actually two independent memories. The 68010 selects which one is used by whom.

Timing For ADSP-2100 System 4 Board
Using Data Sheet for Revised ADSP-2100, August 22, 1986
d Margolin 7/7/86, 7/17/86, 7/29/86, 8/25/86

ord Memory Reads:

Program Memory Address (PMA) Valid to Program Memory Data (PMD) required = .50 ns

Therefore, Program Memory Access Time: 50 ns

Data Memory Address (DMA) Valid to Data Memory Data (DMD) required = 57 ns Therefore, Data Memory Access Time: 57 ns

New Memory Reads:

Program Memory Address (PMA) Valid to Program Memory Data (PMD) required = 50 ns
Therefore, Program Memory Access Time: 50 ns

RAM access = 50 ns - 5 ns (Address Decoding) = 45 ns max

Data Memory Address (DMA) Valid to Data Memory Data (DMD) required = 57 ns Therefore, Data Memory Access Time: 57 ns

RAM access = 57 ns - 10 ns (Address Decoding) = 47 ns max

New Signals:

Data Memory Select (/DMS), same timing as DMA, usable as chip select.

Program Memory Select (/PMS), same timing as PMA, usable as chip select.

Program Memory Read (/PMRD), Read Strobe, usable as output enable. (Note: Fast RAMs do not have a separate output enable.)

PMA Valid to /PMRD Low = 10 ns min /PMRD Low to PMD Required = 37 ns max /PMRD High to PMA Invalid = 16 ns

Data Memory Read (/DMRD), Read Strobe, usable as output enable (Note: Fast RAMs do not have a separate output enable.)

DMA Valid to /DMRD Low = 16 ns /DMRD Low to DMD Required = 40 ns max /DMRD High to DMA Invalid = 16 ns /DMRD Width = 49 ns min

Old Memory Writes:

DMD Out Valid to /DMWR High = 28 ns min OMD Out Valid to /PMWR High = 20 ns min

/PMRD Width = 49 ns min

New Memory Writes:

ID Out Valid to /DMWR High = 28 ns min ID Out Valid to /PMWR High = 20 ns min

Memory Requirements:

Tacc = 45 ns min Address Setup to Write Start = 0 ns Write Pulse Width = 49 ns Data Set up to end of Write = 20 ns max

Cypress 45 ns RAM (CY7C168):

Program Memory Access Time: 50 ns

5 ns memory select + 45 ns RAM access = 50 ns (ok)

Data Memory Access Time: 57 ns

9 ns memory select + 45 ns RAM access = 54 ns (ok)

Program Memory Write pulse: 49 ns

RAM Write pulse = 35 ns (ok)

Data Memory Write pulse = 49 ns

RAM Write pulse = 35 ns (ok)

Data Valid to End of Write = 28 ns DM

ata Valid to End of Write = 20 ns PM

RAM Data Setup to End of Write = 15 ns min (ok)

Data Hold = 22 ns

RAM requirement = 3 ns (ok)

Program Memory Address Setup to Start of Write = 4 ns min
Data Memory Address Setup to Start of Write = 6 ns min

RAM requirement = 0 ns (ok)

Program Memory Address Setup to End of Write = 59 ns min Data Memory Address Setup to End of Write = 64 ns min

RAM requirement = 35 ns

After the ADSP reads the Sequential Input Memory (SIMBUF) and increments the EPROM address, the next memory access has to wait at least 216 ns before it can be read again. [ALS169 = 16ns + 27256 200ns].

For a SIMBUF read followed by a NOP followed by another SIMBUF read:

Start at end of SIMBUF: ALS169 = 16ns, 27256 = 200ns, LS244 = 18 ns.

Total is 234 ns. The data is therefore available 16 ns before the end of the second SIMBUF read. The data must be stable 3 ns before Clk 7/8. The signal that increments the ALS169s is 1 half-clock plus gate delays after Clk 7/8 for total of ~26 ns. The Data must be available 29ns less than 2 major cycles or 221ns. This would require EPROM with 221-16-18 = 187ns.

It is therefore necessary to follow a SIMBUF read with two NOPs (or other instructions) before doing another SIMBUF read.

e alternative is to use 170ns EPROM.

After the ADSP writes to the Sequential Output Memory (SOMD) it must wait at least 1 Instruction cycle before writing to it again.

When it writes to it the Data is captured in a latch which extends the memory write until the end of the next instruction. (The ADSP can be doing another instruction). The Sequential Output Memory is then incremented. (The ALS569 takes 16 ns.)

Major Cycles: Write 1 NOP Write 2

Write Pulse 1

New RAM Address

Write Pulse 2

Write Pulse 2

Bus Request (For Both Program and Data Memories):

BR is recognized during clock cycles 3/4 and tri-states the bus about 2 half-cycles after the next clock cycle 3/4. (about 150 ns total). If BR is asserted during clock cycles 4/5, this will add about 125 ns to the access time for a total of 275 ns worst case.

The 68010 should be able to Set ADSPBR Low and begin accessing memory with its next instruction.

Nitty Gritty

/SIMBUF = Read the Sequential Input Memory and increment the Address Counter.

There is a worst case delay of 9.0 ns from Data Memory Address Valid to /SIMBUF. /DMS low to /DMRD low is 16 ns min, so there will not be any glitches on the clock low. The total delay from /DMRD low to the Counter Clock Input low is 'AS08 + 'AS32 = 9 ns.

/DMRD low to Data Memory Data In Required = 40 ns max (LS244 prop delay is 18 ns max)

/DMRD high to Data Memory Address Invalid is 16 ns min. The Counter Clock Input will go high 9 ns after /DMRD high with no glitches.

All of the decoded writes are strobed by /DMWR and are therefore delayed 8 ns coming and going.

/DMWR high to Address Invalid = 16 ns min /DMWR high to Data Out Invalid = 22 ns min

Therefore the Decoded Writes will go high with both address and data valid.

/SIMLD = Write to the Sequential Input Memory Address Counter

/SIMCLK to load the counters will be delayed an additional 4 ns with no problem.

/SIMLD low will be valid 20 ns before /SIMLD. It will be at least 49 ns bwfore /SIMCLK goes high. The ALS169 has a Load setup time of 15 ns.

SOMLATCH = Write to the Sequential Output Memory Data Latch.

SOMLATCH is delayed 4 ns from the decoded write strobe with no problem. (The LS373 has 0 setup time and 10 ns hold time.)

/SOMD = SOMLATCH decoded address, is guaranteed to be valid when CLKOUT goes high. Generates an extended Memory Write for the 6264s.

CLKIN low (7-8) to CLKOUT high is 8 - 19 ns.

CLKIN high (8-1) to /DMS invalid is 14 ns min.

CLKIN Low (7-8) to CLIKIN high (8-1) is 15 ns so that CLKOUT high must occur (at the very latest) 3 ns after CLKIN high (8-1) which is 16 ns before /DMS invalid.

/XIN = Read the Auxiliary Input Buffer (A decoded Read)

/XOUT = Write to the Auxiliary Output Latch (A Write Pulse)

/GINT = Generate a 68010 Interrupt (A Write Pulse)

/MP = Select the Memory Page (A Write Pulse)

Title / ASSY, SUB, DRIVER ADSP		P/L A044421-01	Rev /	/ в	
GAMES ENGINEERING PARTS LIST SPECIFICATION	PROJECT:	DRIVING SIMULATOR	Page 1	Lof	2



Drawn by: G. POPKIN
Checked by: A.JACKSON

Design Eng: JED MARGOLIN
Proj. Eng: R.MONCRIEF

Mig. Eng: WRIGHINOUR

11			Ind	. Design	1:		Qual. Eng:		
REV	DESCRIE	PTION	DATE	APPR	REV	DESCR	[PTION	DATE	APPR
A B	PRODUCTION REECN 13214		8/88 17-2-2	gm RUU					
ITEM	PART NO	QTY	Descrip	tion			Ref. De	signato	ors
1 2 3 4	044422-01	1	P.C. Board						
5 6 7	122002-104 124008-107	91 1	CAP, .1μF, CAP, 100μF				C2-92 C1		
8	179021-060	1	CONN, HDR,	60 CKT	, 4 WA	LL, .1 X .1C	Jl		
9 10	131027-002	3	DIODE, MV5	053, LIC	GHT EM	IT	CR1-3		
11 12 13 14 15 16 17	144008-002	1	IC, 32MHZ	CLOCK M	ODULE		X1		
18 19 20 21 22 23 24	110000-103 110000-151 110000-102 110000-221	15 2 5 1	RES, 10K, RES, 150, RES, 1K, 5 RES, 220,	5%, 1/4W %, 1/4W	Ň		R1-12,R16-1 R13,R14 R19-23 R15	8	
25 26 27 28	79–42C28 179236–001	4	SOCKET, 28 SOCKET, IC		101 CK	T, LIF	10H,10J,10K ADSP2100	,10L	
29 30	179051-001	6	TEST POINT	ı			+5V1,+5V2,G	ND1-4	
31 32 33 34 35	137517-001 137471-001 137464-001 137476-001	2 4 1 8	IC, 74ALS1 IC, 74ALS3 IC, 74ALS3 IC, 74ALS5	69 2			7B,7C 9L,9K,9J,9H 7A 4A,4B,4C,4D 4H,4J		

Title / ASSY,SUB,DRIVER ADSP

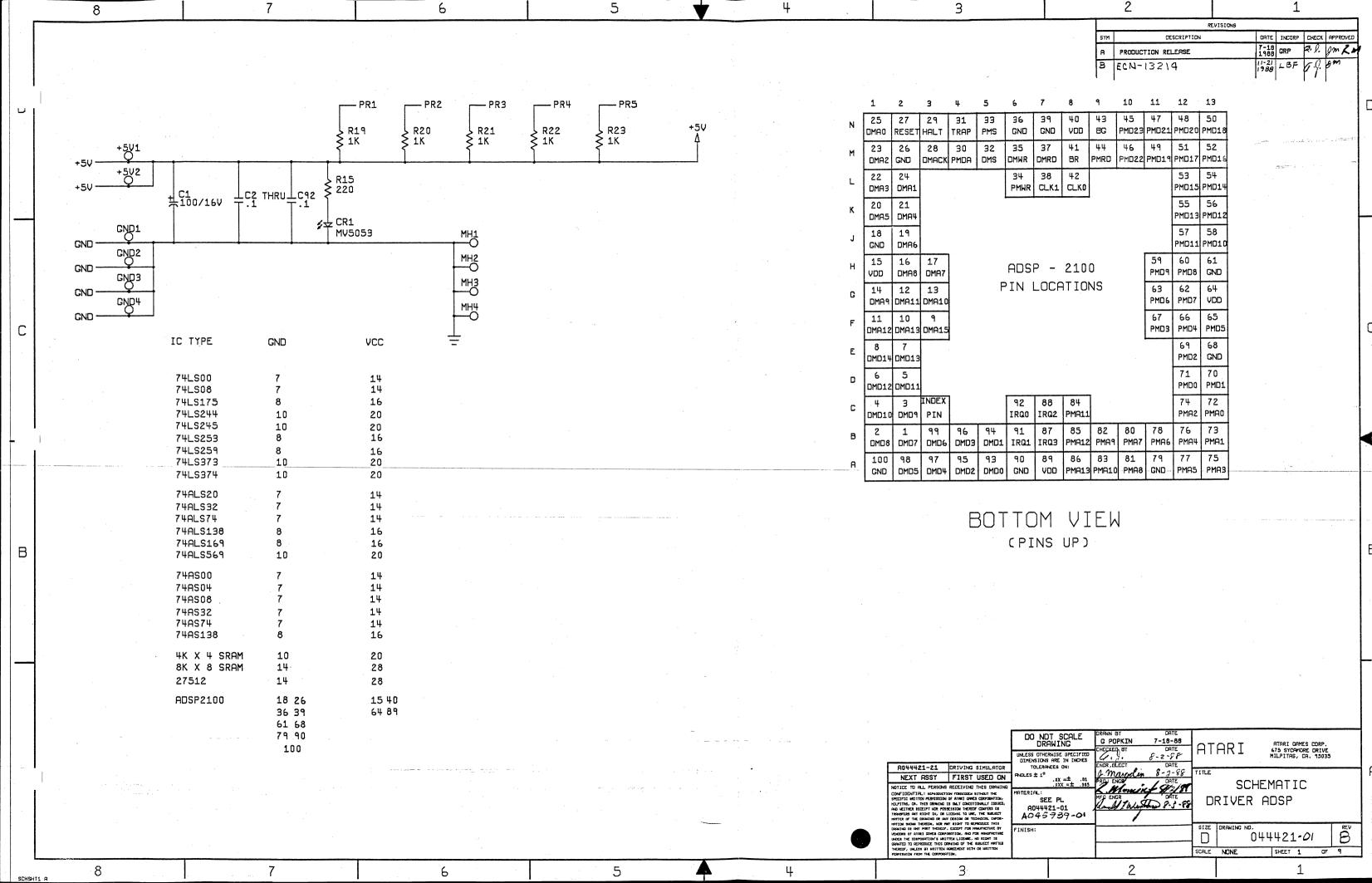
P/L A044421-01

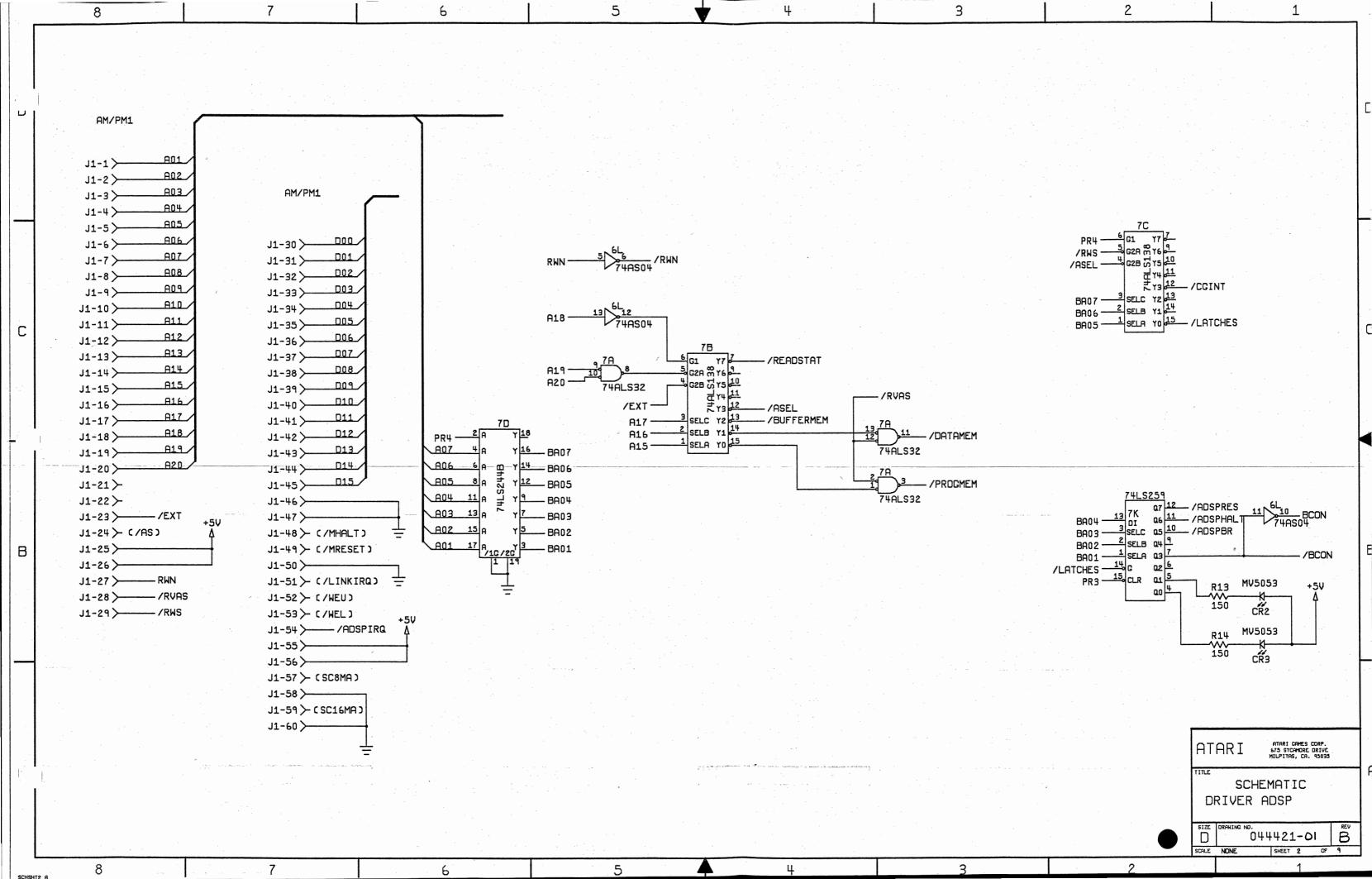
REV / B

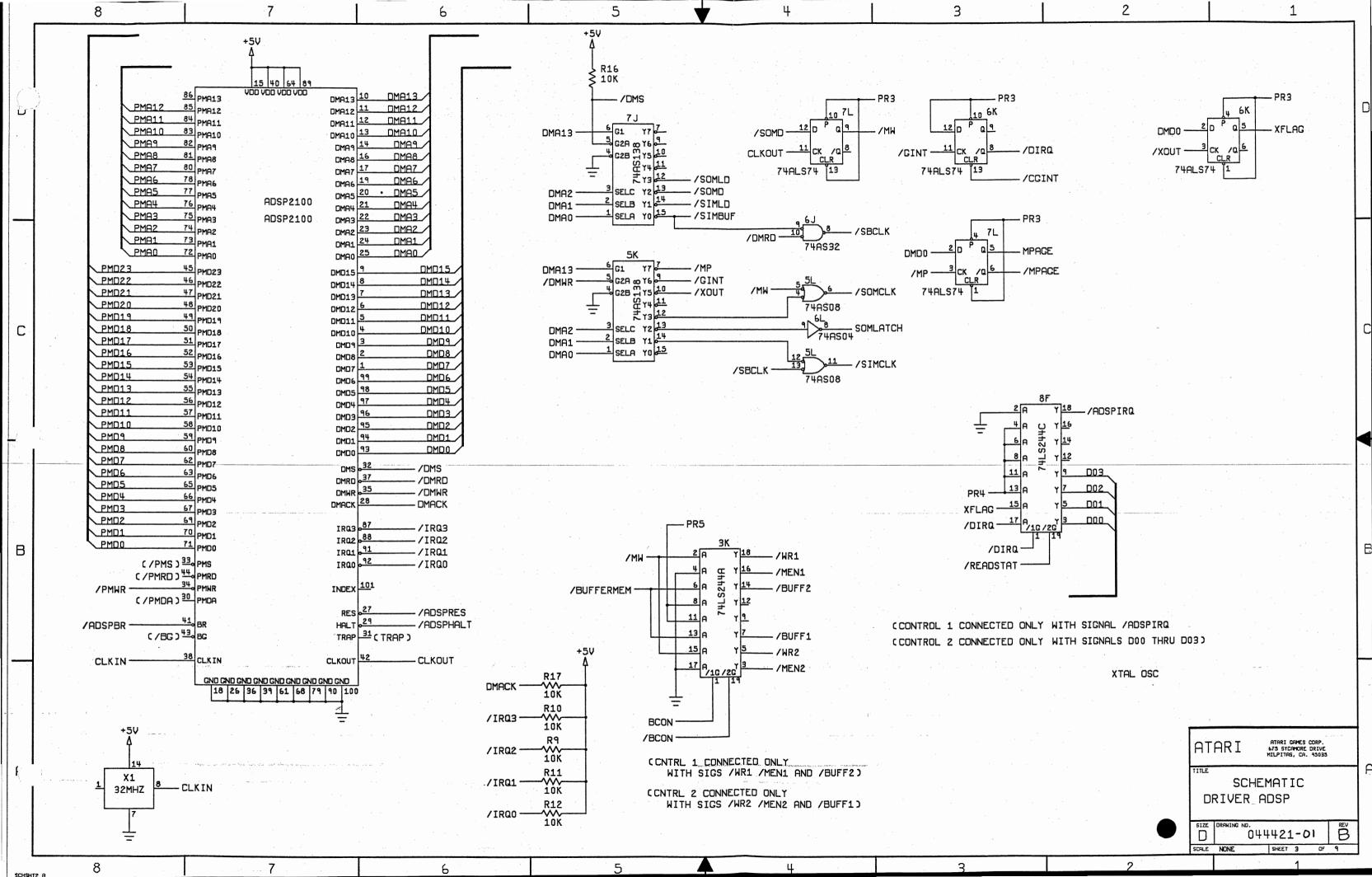
GAMES ENGINEERING
PARTS LIST SPECIFICATION

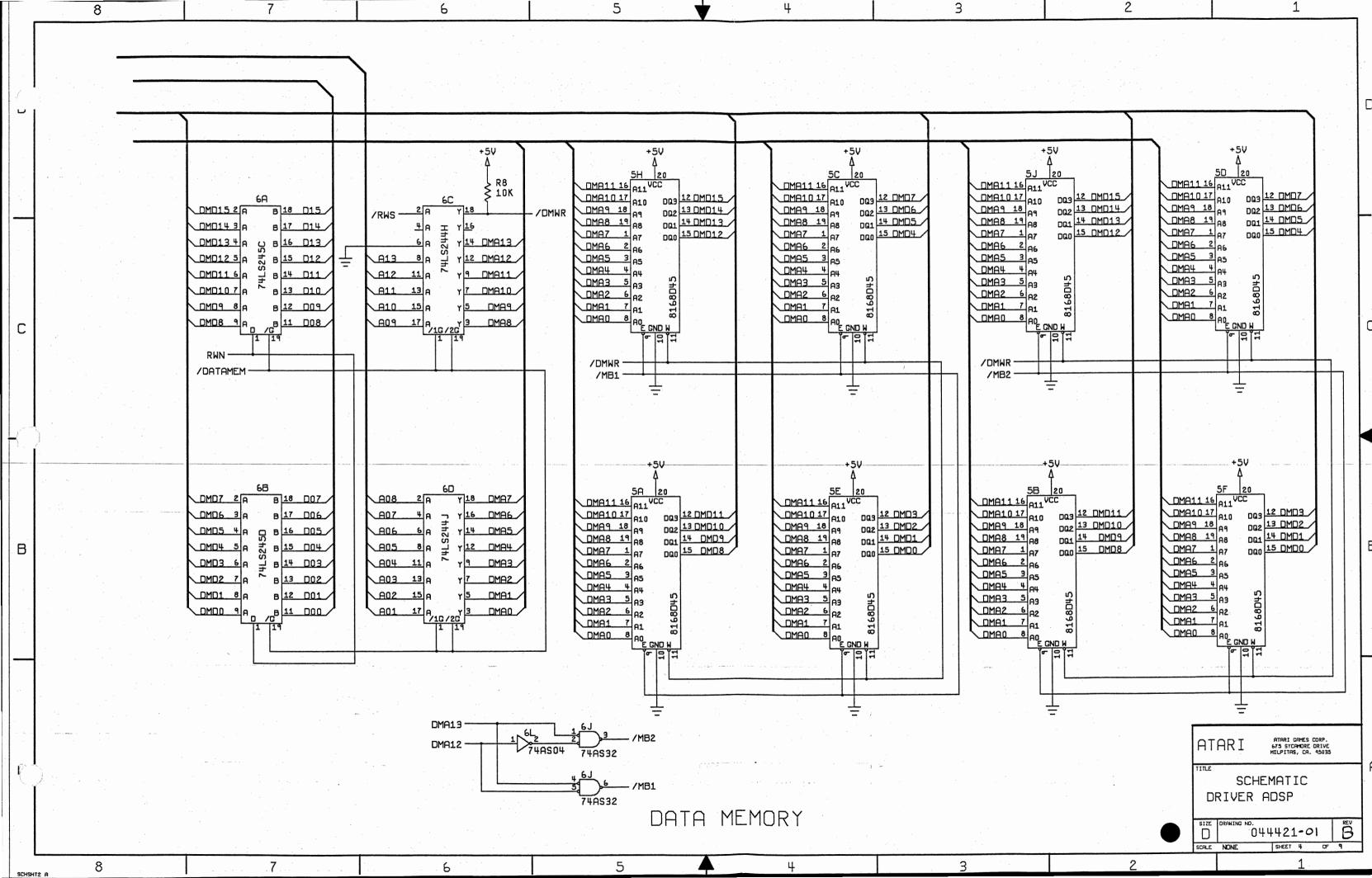
Page 2 of 2

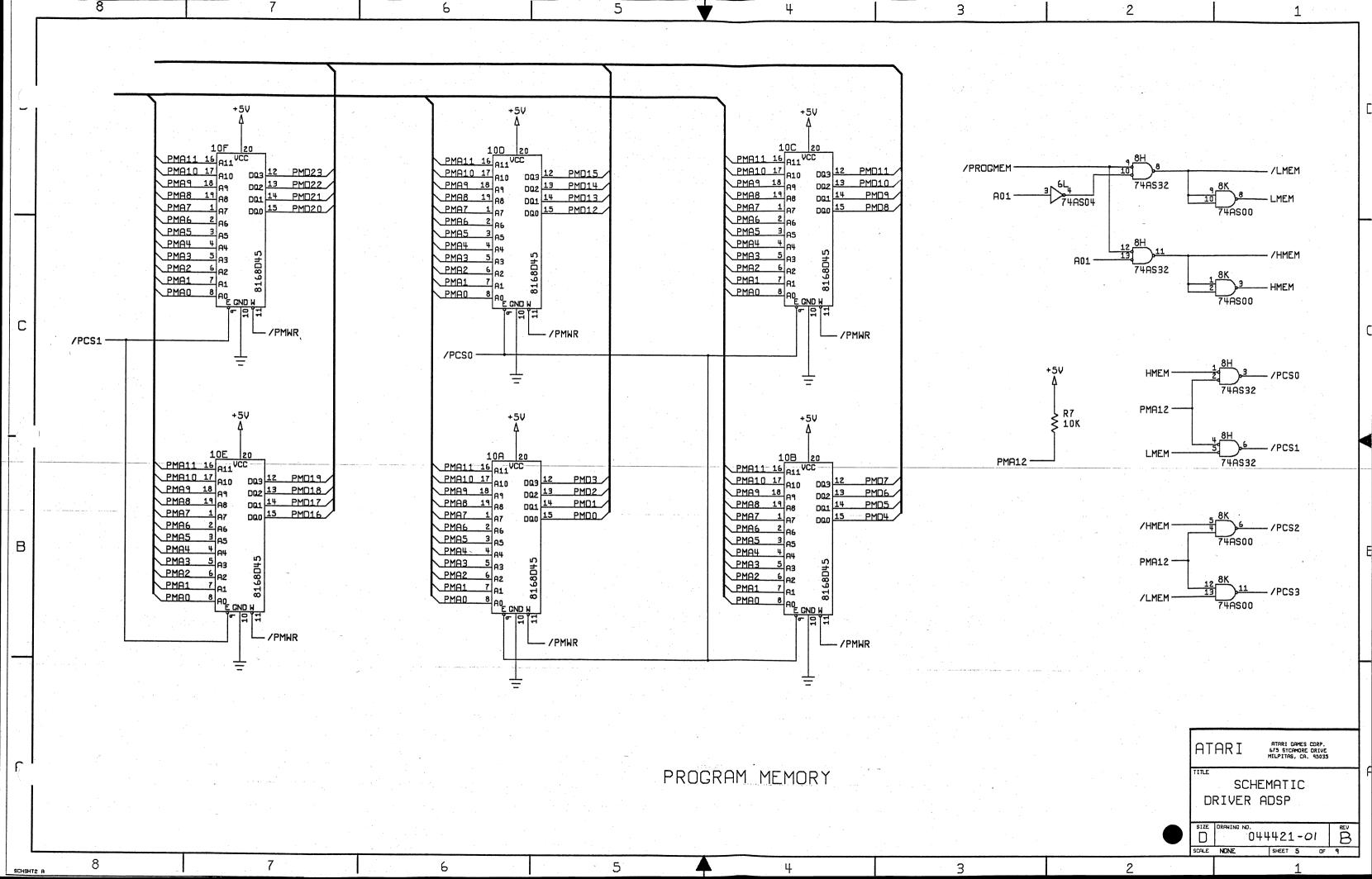
PARTS	LIST SPECIFICA	TION		Page 2 of
TEM	PART NO	QTY	Description	Ref. Designators
36	137156-001	2	IC, 74ALS74	7L,6K
37	137480-001	1	IC, 74AS00	8K
38	137433-001	ī	IC, 74AS04	6L
		ı		5L
39	137484-001		IC, 74AS08	
40	137522-001	2	IC, 74AS138	5K,7J
41	137487-001	2	IC, 74AS32	6J , 8H
42	137038-001	13	IC, 74LS244	3C,3D,3E,3F,3K,6C,
				6D,7D,8C,8D,8F,8J,8L
43	137134-001	9	IC, 74LS245	1D, 1E, 2D, 2E, 6A, 6B,
	10/101 001		207 / 2222 10	8A,8B,8E
44	37-74LS259	١, ١	IC, 74LS259	7K
44		1		
45	137143-001	4	IC, 74LS373	1C,1F,2C,2F
46		l		
47				
48				
49	137537-003	20	IC, SRAM, 4KX4, (8168D45)	5A,5B,5C,5D,5E,5F,5H,
	20,00, 000	-	20, 5111, 1111, (0100)	5J,9A,9B,9C,9D,9E,9F,
				10A,10B,10C,10D,10E,
		1 .	(10F
50	137535-006	4	IC, SRAM, 8KX8, (6264D15)	lh,3h,la/B,3a/B
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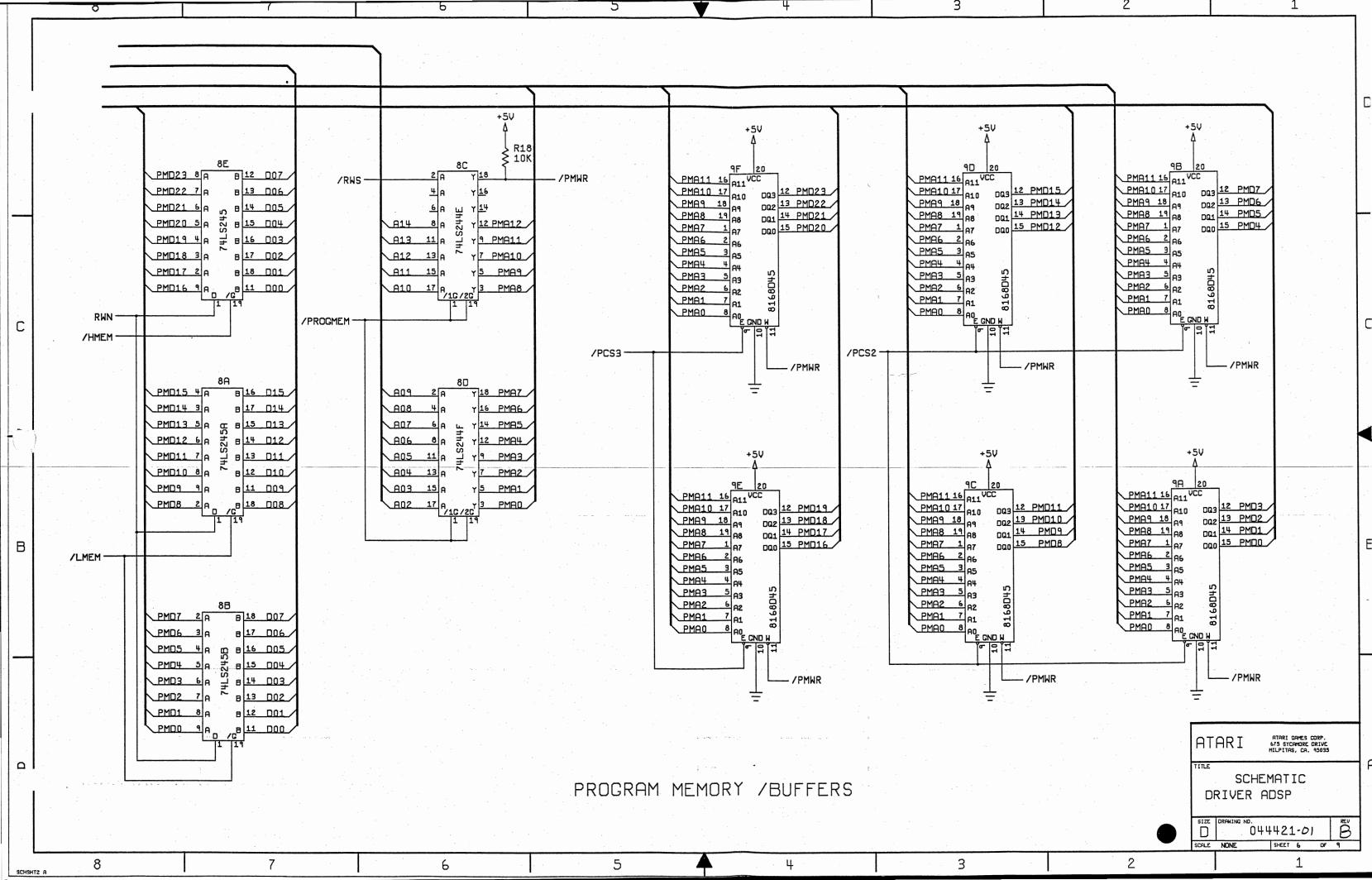


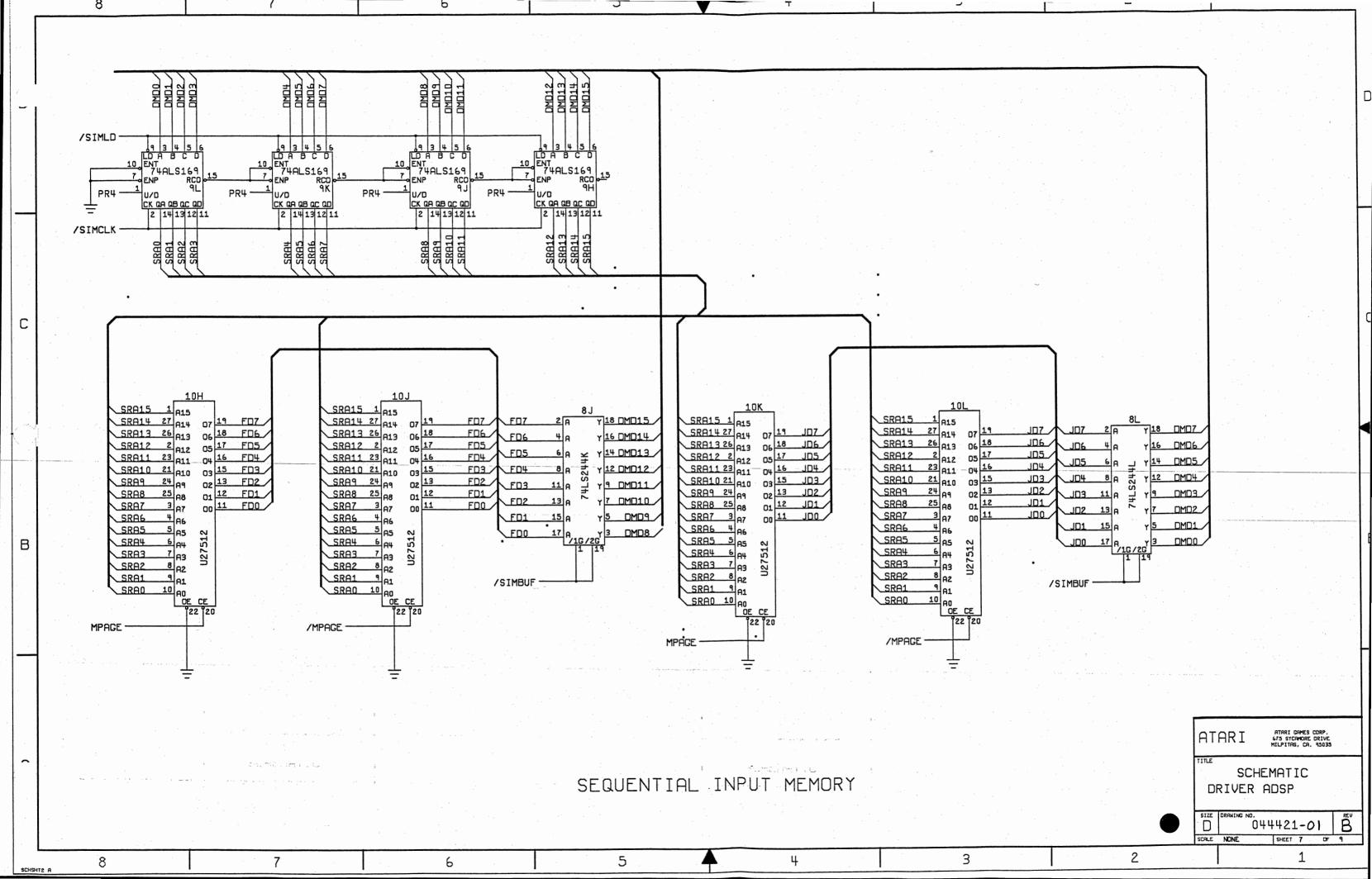


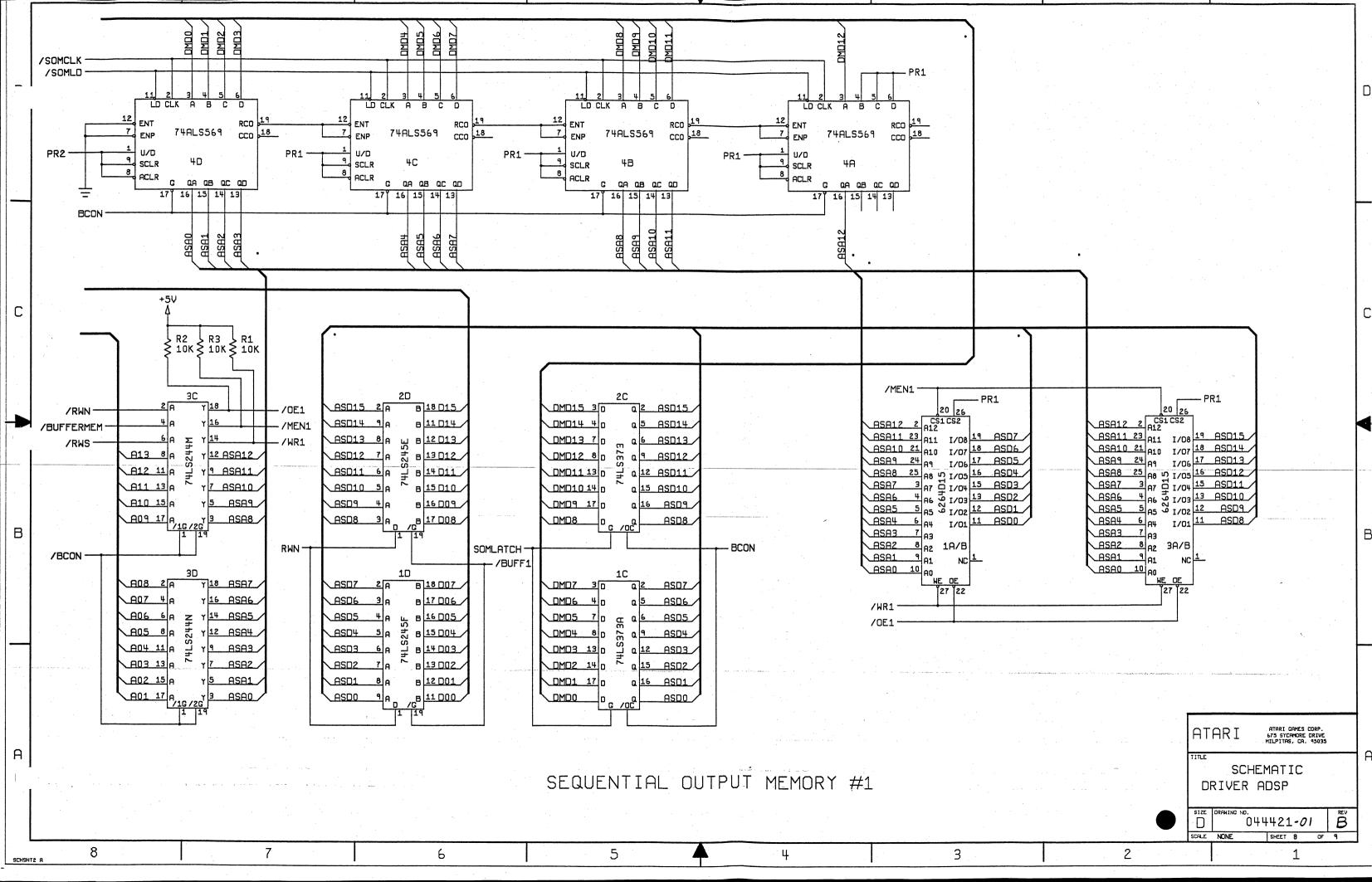


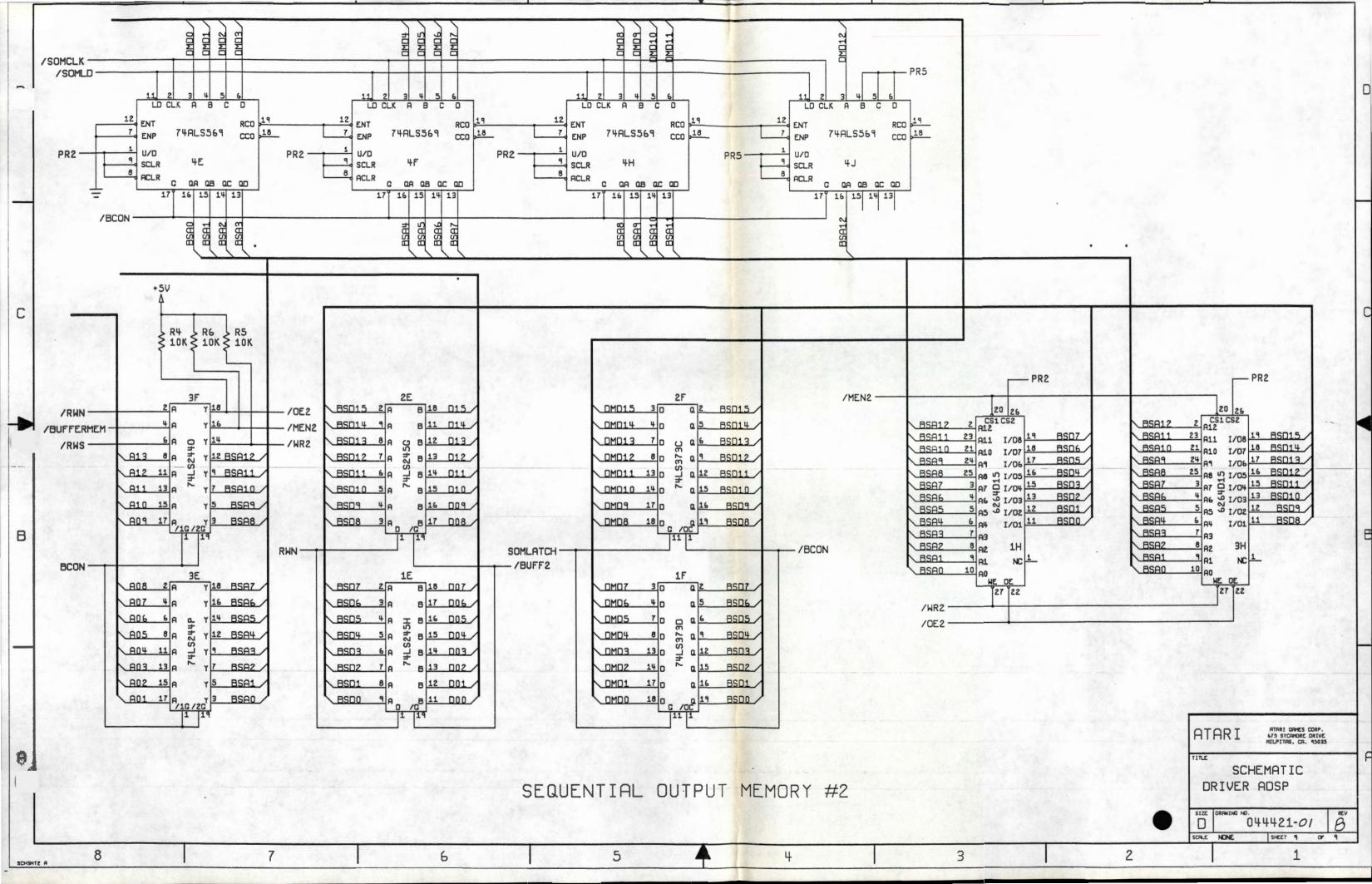












Tab - "ADSP II"

GAMES ENGINEERING PROJECT: H.D.	/ c	C	
PARTS LIST SPECIFICATION Page	1		_



Drawn by: L.FRITTS Next Assy:
Thecked by: A047046-01,02

Design Eng: Comp. Eng:
Proj. Eng: Mfg. Eng:

_		Ilna	. Lesign		Qual. Enq:		
REV	DESCRIPTION	DATE	APPR	REV	DESCRIPTION	DATE	APPR
A B C	PRODUCTION REL REVISED PER ECN 13811 REVISED PER ECN 13954	6/89 4/90 8-10-90	3m				

ITEM	PART NO	QTY	Description	Ref. Designators
1 2 3 4	047048-01	1	P.C. Board	
5 6 7	122002-104 124008-107	94 1	CAP, .1μF, 50V, CER CAP, 100μF, 16V, ELEC	C2-95 C1
8 9 10 11 12	179021-060	1	CONN, HDR, 60 CKT .2 CTR	Jl
13 14 15 16 17	131027-002	3	DIODE, MV5053, LIGHT EMIT	CR1-3
18	144008-002	1	IC, 32MHZ CLOCK MODULE	X1
19 20	137517-001 137464-001	2	IC, 74ALS138 IC, 74ALS32	7B,7C 7A
21	137476-001	8	IC, 74ALS569	4A,4B,4C,4D,4E,4F,4H, 4J
22	137156-001	2	IC, 74ALS74	6K,7L
23	137480-001	1	IC, 74AS00	8K
24	137433-001	1	IC, 74AS04	6L
25 26	137484-001 137522-001	1 2	IC, 74AS08 IC, 74AS138	5L 5K,7J
27	137487-001	2	IC, 74AS32	5K, 75 6J, 8H
28	137097-001	1	IC, 74LS139	8/9J
29	137038-001	13	IC, 74LS244	3C, 3D, 3E, 3F, 3K, 6C, 6D,
30	137134-001	9	IC, 74LS245	7D,8C,8D,8F,8L,8H/J 1D,1E,2D,2E,6A,6B,8A, 8B,8E
31	137137-001	1	IC, 74LS259	7K
32	137143-001	4	IC, 74LS373	1C,1F,2C,2F
33	137537-003	20	IC, SRAM, 4KX4, 45 NS	5A, 5B, 5C, 5D, 5E, 5F, 5H,

Title / ASSY, SUB, ADSP II PCB P/L A047047-01 REV / C GAMES ENGINEERING PROJECT: H.D. PARTS LIST SPECIFICATION Page 2 of ITEM PART NO OTY Ref. Designators Description 5J,9A,9B,9C,9D,9E,9F, 10A, 10B, 10C, 10D, 10E, 10F 8/9K,8/9L,8/9F/H, 137471-001 4 IC, 74ALS169 34 8/9H/J 137535-004 4 IC, RAM, 8KX8, 100 NSEC 1H, 3H, 1A/B, 3A/B 35 36 37 RES, 10K, 5%, 1/4W R1-12,R16-18 110000-103 15 RES, 150, 5%, 1/4W 38 110000-151 2 R13,R14 39 110000-102 7 RES, 1K, 5%, 1/4W R19-23, R48, R49 RES, 220, 5%, 1/4W R15 40 110000-221 1 41 42 43 6 SOCKET, 28 PIN, .600" 44 179257-028 9H, 9K, 10H, 10K, 9/10H, 9/10K45 179288-001 1 HOUSING, SOCKET, PQFP, 100PIN ADSP2100 46 47 48 179051-001 6 TEST POINT +5V1,+5V2,GND1-4

Title / ASSY, ADSP II PCB	P/L A047046-02	Rev / B
GAMES ENGINEERING PARTS LIST SPECIFICATION	PROJECT: H.D. COMPACT	Page 1 of 1



Drawn by: L.FRITTS

Next Assy:

Design Eng: J. MARSOLIN 6-2-69

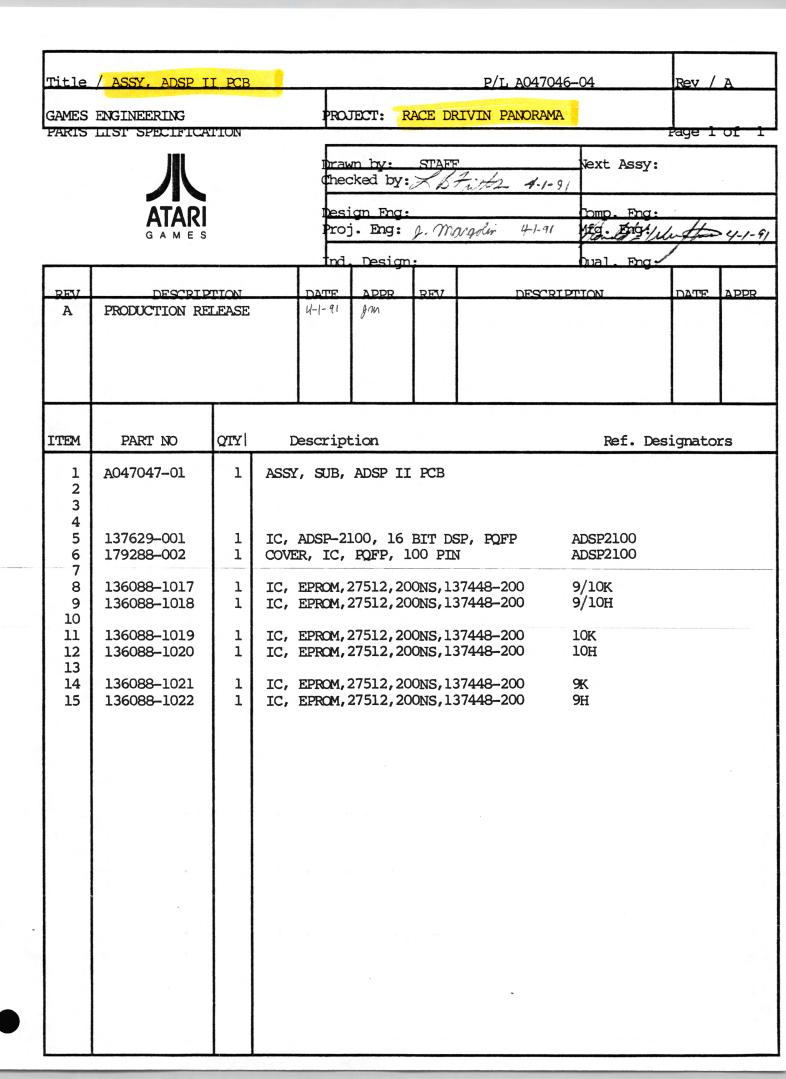
Proj. Eng:

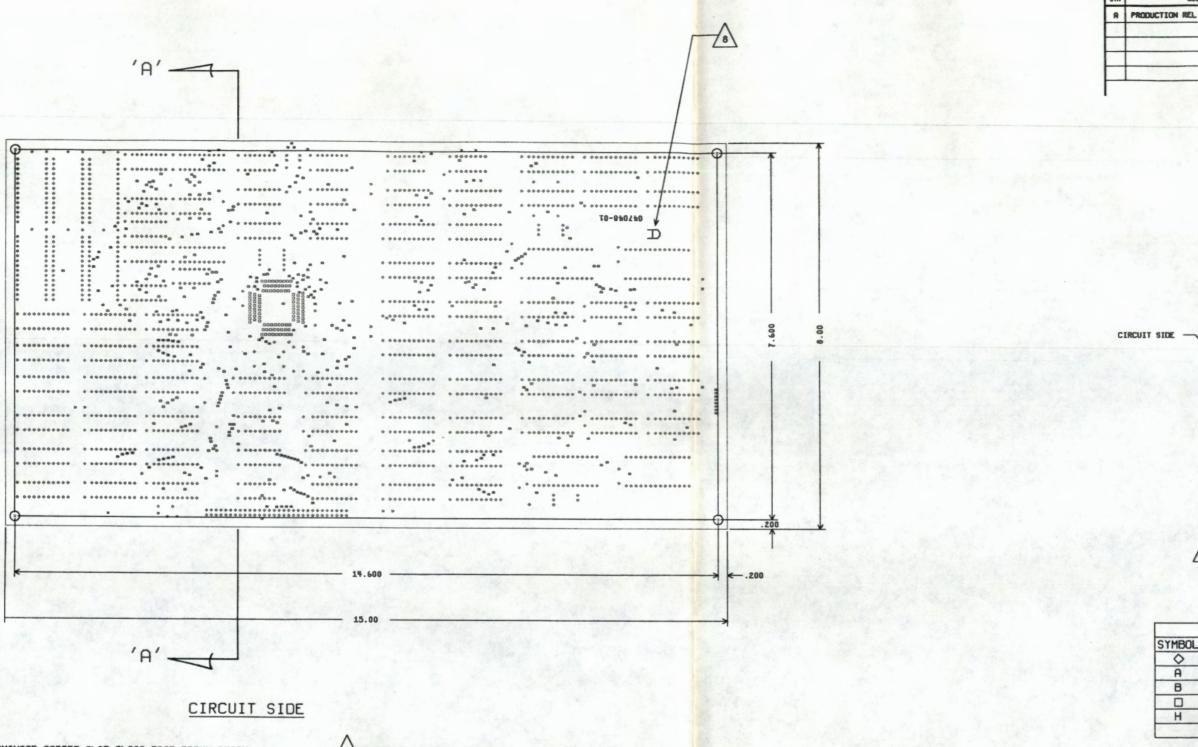
O.W. 6-22-69

Lind Design Prog. Over Design Prog.

	ATARI G A M E S			Pro	ign Eng: j. Eng: . Design		ARGOLIN 6-3	Comp. En Mrg. Eng Qual. En	D.W. 6-	· 22-89
REV A	DESCRIP PRODUCTION RE			TE 89	APPR	REV	DESC	RIPTION	DATE	APPR
В	ECN 13597	-	0,	69	JM .					
ITEM	PART NO	QTY	Desc	rip	tion			Ref.	Designato	rs
1 2 3 4 5	A047047-01 137629-001	1	IC, ADS	SP-2		BIT D	SP, PQFP	ADSP2100		
6 7 8 9 10	179288-002 136052-1136 136052-1135 136052-1138 136052-1137	1 1 1 1	IC, OTF IC, OTF IC, OTF	2, 2 2, 2 2, 2	7C512-25	50, 13 50, 13 50, 13	N 7454–250 7454–250 7454–250 7454–250	9/10K 9/10H 10K 10H		

Title	ASSY, ADSP I	I PCB					P/L A	047046-	-03	Re	ev /	С
1	ENGINEERING	TTON		PRO	JECT: F	1.D. T	HE RACE			- Pac	je l	of 1
FRILL	ATARI	110L		Chec Des Pro	wn by: cked by: ign Eng:	J.D.		./89	Next Ass Comp. Fr	g:		
					. Design		I		Oual. Er			
REV A B C	PRODUCTION RE ECN 14023 ECN 14067	LEASE	90	10-3a-30	gm	REV	D	ESCRI PI	TON	DA	ATE	APPR
ITEM	PART NO	QTY	Ι	Descrip	tion				Ref.	Design	nato	rs
1 2 3 4 5 6 7 8 9 10	A047047-01 137629-001 179288-002 136077-2021 136077-2023 136077-2024	1 1 1 1 1 1	IC, COVE IC, IC, IC,	ADSP-2 ER, IC, EPROM, EPROM, EPROM,	POFP, 27512, 25 27512 25 27512 25	BIT D 100 PI 50NS,1 50NS,1	SP, PQFP N 37448-250 37448-250 37448-250) 9) 9	ADSP2100 ADSP2100 9/10H LOH 9/10K LOK			





NOTES:

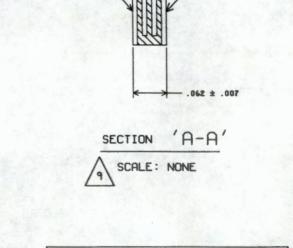
- MATERIAL: BASE LAMINATE, COPPER CLAD GLASS BASE, EPOXY RESIN,
 FLAME RETARDANT, 1 OZ COPPER ON ALL INTERNAL LAYERS, 1 OZ COPPER
 ON EXTERNAL LAYERS SHALL BE IN ACCORDANCE WITH MIL-P-55617.
 BONDING AGENT: PRE-IMPRECNATED-B STAGE (UNCURED RESIN SHEET)
 SHALL BE IN ACCORDANCE WITH IPC-L-110.
- 2. PLATING: SOLDER PLATE, INCLUDING PC FINGERS (CONNECTOR).
- 3. MAX. THIST OF WARP PERMITTED IS . 005 PER INCH.
- 4. VENDOR LOGO TO BE ADDED TO BOARD IN CLEAR AREA.
- 5. SOLDERMASK BOARD WITH PC-401 OR EQUIV, BOTH SIDES.
- FABRICATE PER ATARI PC BOARD MANUFACTURING SPECIFICATION 190012.
- 7. SILK SCREEEN COMPONENT SIDE OF BOARD USING PERMANENT-TYPE YELLOW EPOXY INK.

SHOWN ON CIRCUIT SIDE.

AS VIEWED FROM THE COMPONENT SIDE, LAYER SEQUENCE NUMBERS
MUST READ IN ORDER 'COMP, 2, 3, CIRCUIT'.

10 TOOLING HOLES TO BE CLEAR OF SOLDERMASK .50 DIA., MPLCS.

- 11. BOARD TO BE FABRICATED USING 'FINE LINE' TECHNOLOGY.
 MAXIMUM OVER-ETCH ALLOHED .0020
 MAXIMUM UNDER-ETCH ALLOHED .0010
- 12. ALL BOARDS TO BE 100% ELECTRICALLY TESTED FOR SHORTS AND OPENS.



DESCRIPTION

DATE INCORP CHECK APPROVE

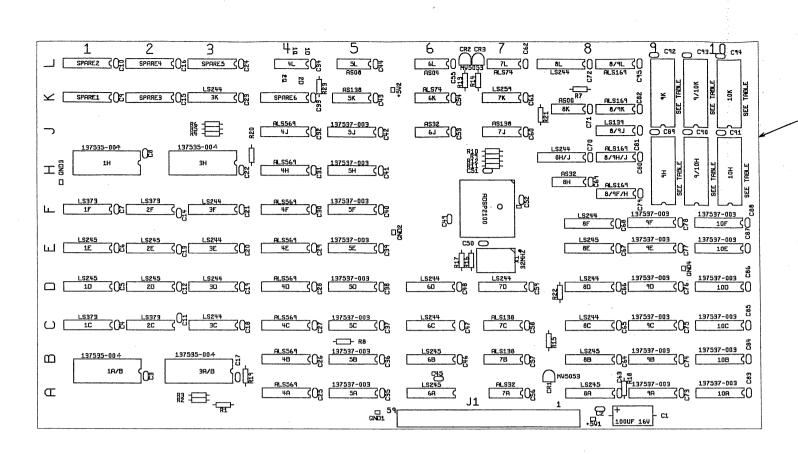
LAYER 3 (+5V)

- COMP SIDE

6-21 1989 LBF JD pm

SYMBOL	FINISHED DIA	QTY	PLATED
\Q	.040 ±.003	2068	YES
A	.047 ±.003	24	YES
В	.028 ±.003	442	YES
	.026 ±.002	100	YES
Н	.191 ± .003	4	YES

A047047-01 DRIVER SIMULATOR		DO NOT SCALE DRAWING UNLES OFFICE FIELD DISCONDING FRE IN UNCES TOLERANCES DIS-	DECKED BY J.DIEU	OATE 6-21-89 OATE 6-21-89	ATARI			
NEXT ASSY	FIRST USED ON	RECEST 10 W -+	1 margolin G-31	G-31- 89	TITLE			
MOTICE TO REL PERSONS RECEIVED THE COMMUNICATION OF THE PROPERTY OF THE PROPER		XX = ± .01 XXX = ± .005 PRITERIAL: SEE NOTE 1.	PRIJ ENDR	DATE	FABRICATION, ADSP II PCB			
		SEE NOTE 2.	/		SIZE DRAWING NO.	048-01	- A	



REVISIONS							
SYM	DESCRIPTION	DATE	INCORP	CHECK	APPROVED		
А	PRODUCTION RELEASE	6-21 1989	LBF	JD	JM		
В	REVISED PER ECN 13811	3-29 90	DIEU	01.	gan		
C	ECN 13954	7-31	LBF	e li	am		

COMPONENT SIDE

NOTES: FOR ASSY'S A047046-01,-02 AND -03

- 1. INSTRUCTIONS FOR ASSEMBLY OF ADSP2100 DEVICE.
- 1. ALIGN THE PIN NO. 1 IDENTIFIER ON THE PQFP (ITEM5) WITH TRIANGULAR IDENTIFIER ON THE RYTON COVER (ITEM 6). FULLY INSERT THE PQFP. A CLICK WILL BE AUDIBLE. BE SURE ALL LEADS OF THE PQFP ARE LOCATED IN THE ALIGNMENT COMBS ON THE UNDERSIDE OF THE COVER.
- B. PLACE THE COVER ON THE HOUSING BEING SURE TO MATCH THE CHAMFERED CORNER ON THE COVER WITH THE CHAMFERED CORNER ON THE HOUSING.
- C. BEING SURE NOT TO PUSH ON THE PQFP ITSELF, PUSH WITH
 YOUR THUMBS ON THO (2) OPPOSITE SIDES OF THE COVER UNTIL
 THE COVER IS FULLY SEATED, CHECK TO SEE THAT NO GAP EXISTS
 BETHEEN THE COVER AND THE HOUSING.
- D. IT MAY BE NECESSARY TO REPEAT STEP C. USING THE OTHER TWO OPPOSITE SIDES OF THE COVER.
- 2. INSTRUCTIONS FOR DISASSEMBLY OF ADSP2100 (IF EXTRACTION TOOL IS NOT AVAILABLE)
- A. TO DISASSEMBLE, PRY COVER FROM SOCKET HOUSING USING A

 SMALL SCREWDRIVER OR FLAT BLADE. (CORNER EDGE UNDERCUT IN (3)

 THREE PLACES. PRY IN A ROTATING FASHION.)
- REMOVE PQFP FROM COVER USING FINGER PRESSURE, BEING CAREFUL NOT TO BEND LEADS ON PQFP.

		DO NOT SCALE DRAWING	DRAWN BY L.FRITTS CHECKED BY	DATE 6-21-89 DATE	ATART	ATARI CAMES CORP. 675 SYCAMORE DRIVE	
		UNLESS OTHERHISE SPECIFIED DIMENSIONS ARE IN INCHES	J.DIEU	6-21-8		MILPITAS,CA 95035	
A047046	DRIVING SIMULATOR	TOLERANCES ON:	ENGR,ELECT	DATE 6-21-89	TITLE		
NEXT ASSY	FIRST USED ON	ANGLES ± 10 .xx =± .01	J MARGOLIN PROJENCR	DATE	"" DSSF	EMBLY,	l
NOTICE TO ALL PERSONS RECEIVING THIS DRAWING CONFIDENTIAL: MARGONETING PORTION HITHOUT THE		.xxx =± .005 MATERIAL:	, ,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		1,1001	_110_1/	1
SPECIFIC MITTEN PONISSION MILPITHS, CR. THIS ORNING I AND MILTHER RECEIPT HER PURS	OF RITHEL OFFICE COMPONITION, IS COLLY CONCULTABLELY ISSUED, CONTINUE THEORET CONTINUE OR	SEE P/L A047047-01	MFG ENGR D WRIGHTNOUR	DATE 6-22-89	ADSP	II PCB	
PRITICAL SHOWN THEREON, NOR PART RIGHT TO REPRODUCE THIS		A047046-01,02,03					
		FINISH:			SIZE DRAWING NO.	7 04	REU
UNION THE COMPONENTIAN'S INSTITUTE LICENSE, HE SIGHT IS COMMITTED TO REPRODUCE THIS COMMITTED OF THE BUSINESS PORTION					U H04/(J47-U1	
THERETY, UNLINE BY WRITTEN ROWCENENT WITH OR SKITTEN PERMISSION FROM THE COMPONITION.					SCALE 1:1	SHEET 1 OF	1

